

Amendments to the Specification

Please replace the paragraph beginning on page 24, line 5, with the following rewritten paragraph:

Reference is now made to FIG. 7 to describe an example of the circuit configuration of the coupler 22G. The coupler 22G of FIG. 7 has an input terminal 171, an output terminal 172, a monitor terminal 173 and a load connecting terminal 174. The coupler 22G further has: a capacitor ~~174~~ 175 having an end connected to the input terminal 171 and the other end connected to the monitor terminal 173; an inductor 176 having an end connected to the input terminal 171 and the other end connected to the output terminal 172; an inductor 177 having an end connected to the monitor terminal 173 and the other end connected to the load connecting terminal 174; and a capacitor 178 having an end connected to the output terminal 172 and the other end connected to the load connecting terminal 174. The monitor terminal 173 is connected to the input of the automatic power control circuit 23G. The load connecting terminal 174 is grounded through a load of 50 ohms. Each of the couplers 22D, 33W and 33N has a circuit configuration the same as that of the coupler 22G.

Please replace the paragraph beginning on page 52, line 4, with the following rewritten paragraph:

As thus described, the front end module ~~2~~ 302 of the embodiment comprises: the diplexer 310 for separating the AMPS band from the PCS band; the diplexer 312 for separating transmission signals and reception signals in the AMPS band from each other; the diplexer 313 for separating transmission signals and reception signals in the PCS band from each other; and the BPF 314 for selectively allowing reception signals of the GPS to pass therethrough. The diplexer 312 includes the two acoustic wave elements each of which functions as a filter. The diplexer 313 includes the two acoustic wave elements each of which functions as a filter, too. In the embodiment the diplexer 310, the duplexers 312 and

313, and the BPF 314 are integrated on the multi-layer substrate 430. The diplexer 310 is made up of the conductor layer located inside or on the surface of the multi-layer substrate 430.